TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

# **TPC8210**

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

• Low drain-source ON resistance:  $RDS(ON) = 11 \text{ m}\Omega(typ.)$ 

• High forward transfer admittance:  $|Y_{fs}| = 13 \text{ S (typ.)}$ 

• Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$ 

• Enhancement-mode:  $V_{th} = 1.3 \text{ to } 2.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ 

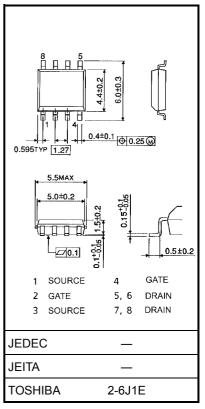
### **Maximum Ratings (Ta = 25°C)**

Char	racteristics	Symbol	Rating	Unit		
Drain-source vol	tage	$V_{DSS}$	30	V		
Drain-gate voltag	ge (R <sub>GS</sub> = 20 kΩ)	V <sub>DGR</sub>	30	V		
Gate-source volt	age	V <sub>GSS</sub>	±20	V		
Drain current	D C (Note 1)	I <sub>D</sub>	8	Α		
	Pulse (Note 1)	I <sub>DP</sub>	32	A		
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.5	W		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D(2)</sub>	1.1	VV		
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.75	W		
	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	0.45			
Single pulse ava	lanche energy (Note 4)	E <sub>AS</sub>	83.2	mJ		
Avalanche curre	nt	I <sub>AR</sub>	8	Α		
Repetitive avalar Single-device va	nche energy lue at dual operation (Note 2a, 3b, 5)	E <sub>AR</sub>	0.1	mJ		
Channel tempera	ature	T <sub>ch</sub>	150	°C		
Storage tempera	ture range	T <sub>stg</sub>	-55 to 150	°C		

Note: For (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5), please refer to the next page.

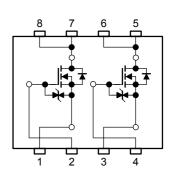
This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm



Weight: 0.08 g (typ.)

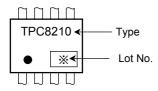
# **Circuit Configuration**



### **Thermal Characteristics**

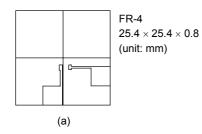
Characteristics	Symbol	Max	Unit		
The small resistance about 140 cushicut	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	83.3		
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th</sub> (ch-a) (2)	114 °C/W		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	167	C/VV	
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	278		

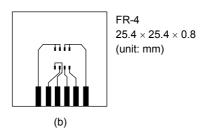
## Marking (Note 6)



Note 1: Please use devices on condition that the channel temperature is below 150°C.

#### Note 2:

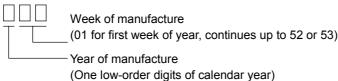




- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)

### Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device. (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device. (During dual operation, power is evenly applied to both devices.)
- Note 4:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (initial), L = 1.0 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 8 A
- Note 5: Repetitive rating: pulse width limited by maximum channel temperature
- Note 6: on lower left of the marking indicates Pin 1.
  - Weekly code: (Three digits)



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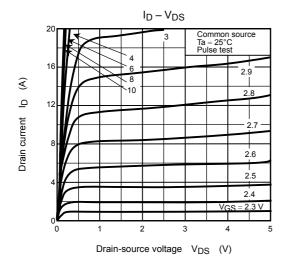
# Electrical Characteristics (Ta = 25°C)

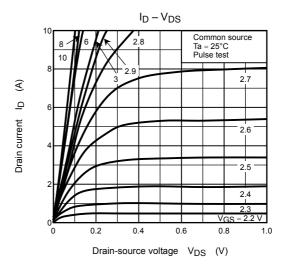
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-OFF	Drain cut-OFF current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V		_	10	μA
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	30	_	I	V
		V <sub>(BR) DSS</sub>	$I_D$ = 10 mA, $V_{GS}$ = -20 V	15	_		
Gate threshold v	oltage/	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.3	_	2.5	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 4 A		13	20	mO.
Drain-source ON resistance		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 4 A		11	15	mΩ
Forward transfer	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 4 A	6.5	13	_	S
Input capacitano	e	C <sub>iss</sub>		_	3530	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	495	_	pF
Output capacitance		Coss		_	580	_	
Switching time	Rise time	tr	$V_{GS}$ $\begin{array}{c} 10 \text{ V} \\ 0 \text{ V} \\ \end{array}$ $\begin{array}{c} I_{D} = 4 \text{ A} \\ 0 \text{ VOUT} \\ \end{array}$ $\begin{array}{c} V_{C} \\ V_{C} \\ \end{array}$ $\begin{array}{c} V_{C} \\ V_$		26	-	
	Turn-ON time	t <sub>on</sub>		1	39	ı	ns
	Fall time	t <sub>f</sub>			32	-	
	Turn-OFF time	t <sub>off</sub>			115	-	
Total gate charge (Gate-source plus gate-drain)		Qg	V <sub>DD</sub> ≈ 24 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 8 A	_	75	_	
Gate-source charge		$Q_{gs}$		_	6	_	nC
Gate-drain ("miller") charge		$Q_{gd}$		_	19	_	

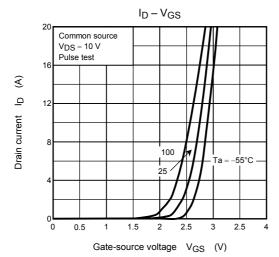
# **Source-Drain Ratings and Characteristics (Ta = 25°C)**

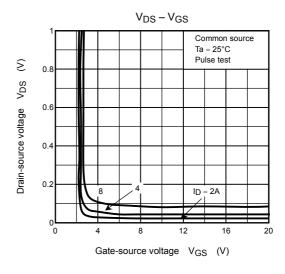
Characte	eristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	32	Α
Forward voltage (diode) V <sub>DSF</sub>		$V_{DSF}$	I <sub>DR</sub> = 8 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V

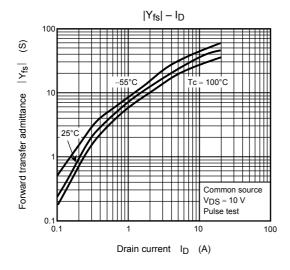
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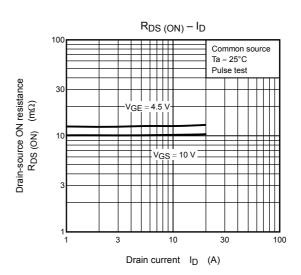


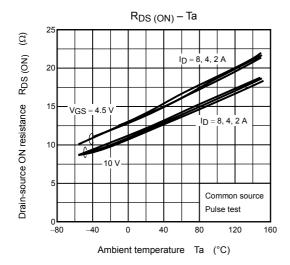


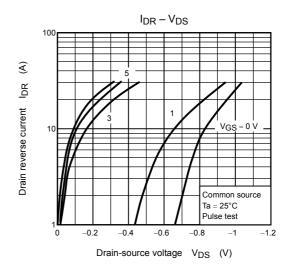


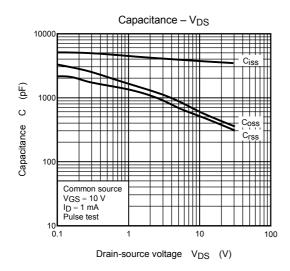


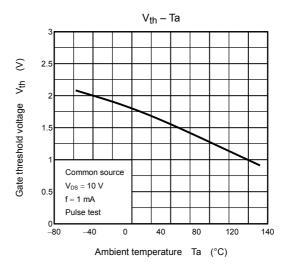


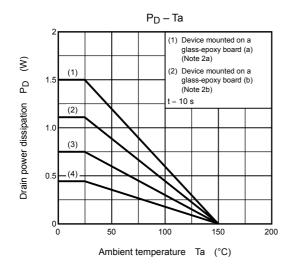


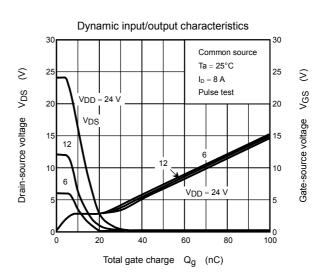


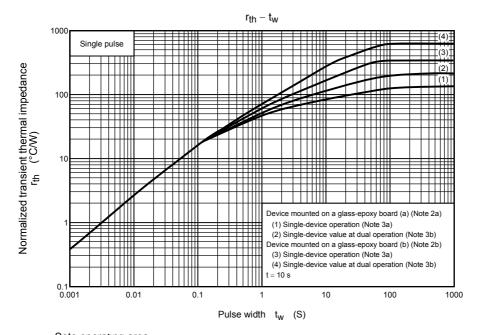


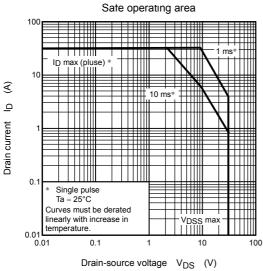












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